

WHAT IS CLAIMED IS:

1. For use with an integrated circuit package having first and second signal transmission zones, a characteristic impedance equalizer, comprising:

a first conductor having a first width and providing a characteristic impedance within said first signal transmission zone; and

a second conductor, coupled to said first conductor, having a second width and providing substantially said characteristic impedance within said second signal transmission zone.

2. The characteristic impedance equalizer as recited in Claim 1 further comprising a plurality of said first and second conductors coupled to a substrate.

3. The characteristic impedance equalizer as recited in Claim 1 wherein said first signal transmission zone is provided between a portion of said substrate containing said first conductor and a metallic heatspreader.

4. The characteristic impedance equalizer as recited in  
2 Claim 1 wherein said second signal transmission zone is provided  
3 between a portion of said substrate containing said second  
4 conductor and a metallic stiffener.

5. The characteristic impedance equalizer as recited in  
2 Claim 1 wherein said first width is greater than said second width.

6. The characteristic impedance equalizer as recited in  
2 Claim 1 wherein a junction between said first conductor and said  
3 second conductor has a semi-circular cross-sectional area.

7. The characteristic impedance equalizer as recited in  
2 Claim 1 wherein said first and second conductors provide a  
3 transmission path for a signal transmission.

8. A method of manufacturing an integrated circuit package,  
comprising:

providing a substrate configured to be partitioned into first  
and second signal transmission zones;

forming a first conductor having a first width and providing  
a characteristic impedance within said first signal transmission  
zone; and

forming a second conductor having a second width and providing  
substantially said characteristic impedance within said second  
signal transmission zone.

9. The method of manufacturing as recited in Claim 8 further  
comprising forming a plurality of said first and second conductors.

10. The method of manufacturing as recited in Claim 8 further  
comprising positioning a metallic heatspreader over a portion of  
said substrate containing said first conductor and forming said  
first signal transmission zone.

11. The method of manufacturing as recited in Claim 8 further  
comprising positioning a metallic stiffener over a portion of said  
substrate containing said second conductor and forming said second  
signal transmission zone.



15. An integrated circuit package, comprising:

a substrate configured to be partitioned into first and second  
signal transmission zones; and

a characteristic impedance equalizer, including:

a first conductor having a first width providing a  
characteristic impedance within said first signal transmission  
zone, and

a second conductor having a second width providing  
substantially said characteristic impedance within said second  
signal transmission zone.

16. The integrated circuit package as recited in Claim 15  
wherein said characteristic impedance equalizer contains a  
plurality of said first and second conductors.

17. The integrated circuit package as recited in Claim 15  
further comprising a metallic heatspreader and said first signal  
transmission zone is provided between a portion of said substrate  
containing said first conductor and said metallic heatspreader.

18. The integrated circuit package as recited in Claim 15  
2 further comprising a metallic stiffener and said second signal  
3 transmission zone is provided between a portion of said substrate  
4 containing said second conductor and said metallic stiffener.

19. The integrated circuit package as recited in Claim 15  
2 wherein said first width is greater than said second width.

20. The integrated circuit package as recited in Claim 15  
2 wherein a junction between said first conductor and said second  
3 conductor has a semi-circular cross-sectional area.

21. The integrated circuit package as recited in Claim 15  
2 wherein said first and second conductors provide a transmission  
3 path for a signal transmission.